

# Specification of Thermoelectric Module

TEFC1-03124

## Description

The 31 couples, 8.3 mm × 8.3 mm size single module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

## Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

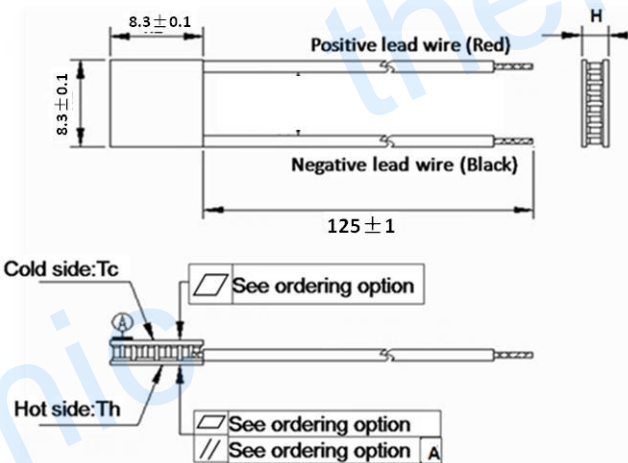
## Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

## Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	3.94	4.30	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (amps)	2.7	2.7	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	6.58	7.07	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	1.10	1.21	The module resistance is tested under AC
Tolerance (%)	10%		For thermal and electricity parameters

## Geometric Characteristics Dimensions in millimeters



## Ordering Option

Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 1.8±0.1	0: 0.03/0.03	125 ± 1/Specify
TF	1: 1.8±0.03	1: 0.015/0.015	125 ± 1/Specify

Eg. TF01: Thickness 1.8±0.1(mm) and Flatness 0.015 / 0.015 (mm)

## Manufacturing Options

### A. Solder:

1. T100: BiSn (T<sub>melt</sub>=138°C)
2. T200: CuAgSn (T<sub>melt</sub> = 217°C)
3. T240: SbSn (T<sub>melt</sub> = 240°C)

### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
2. Aluminum Nitride (AlN)

### B. Sealant:

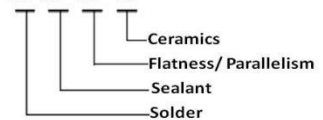
1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

### D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

## Naming for the Module

TEFC1- 03124- X -X - X - X



TEFC1- 03124-T100-NS -TF01 -AIO

T100: BiSn (T<sub>melt</sub>=138°C)

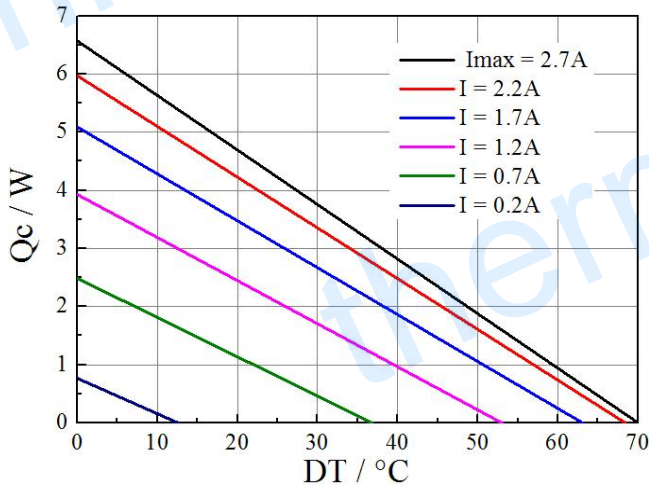
NS: No sealing

AIO: Alumina, white 96%

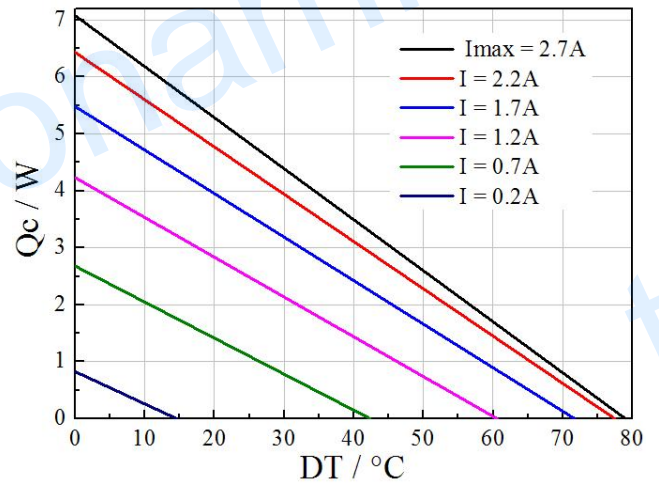
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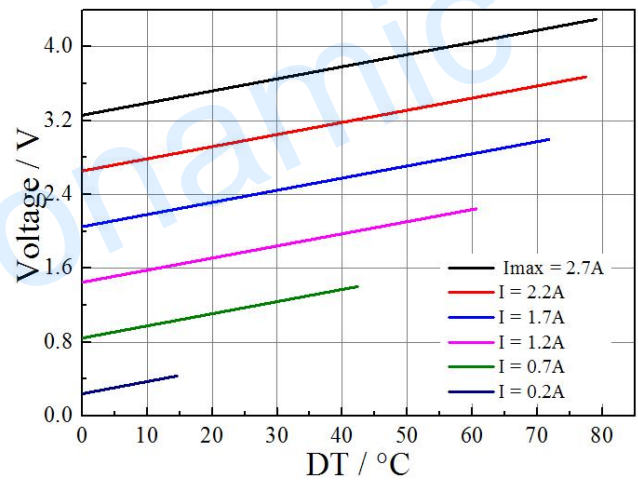
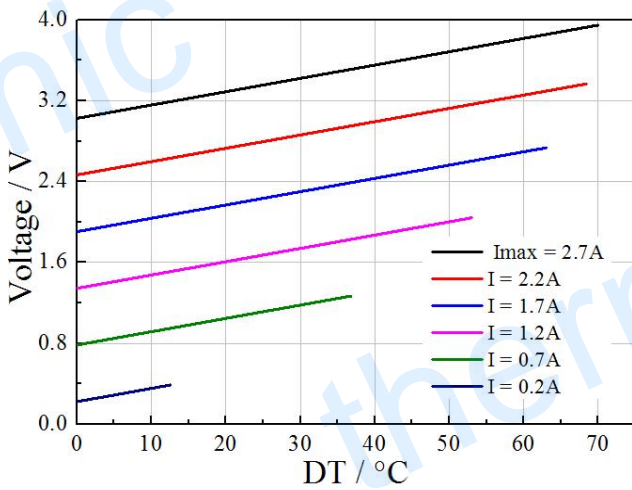
## Performance Curves at Th=27 °C



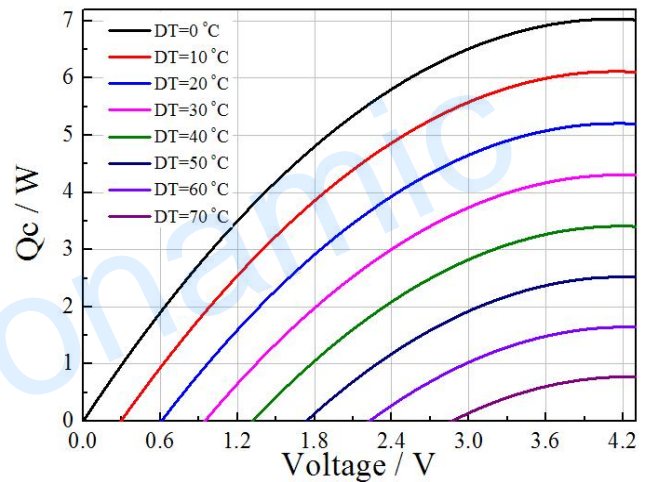
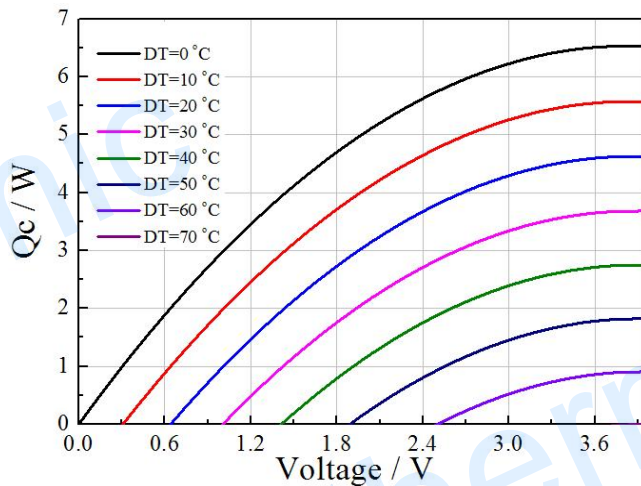
## Performance Curves at Th=50 °C



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(DT)$

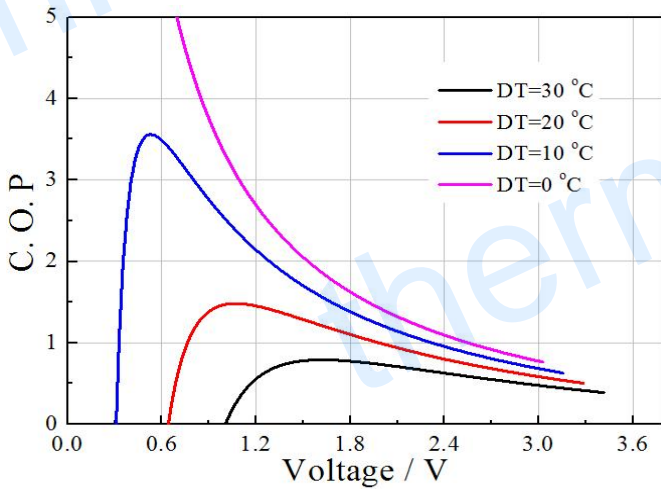


Standard Performance Graph  $Q_c = f(V)$

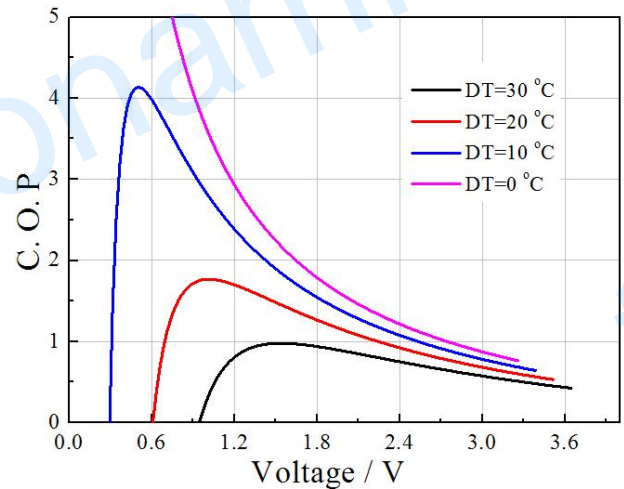
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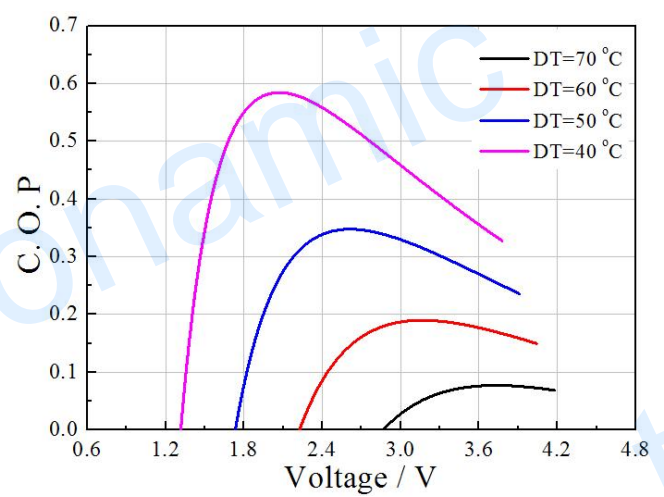
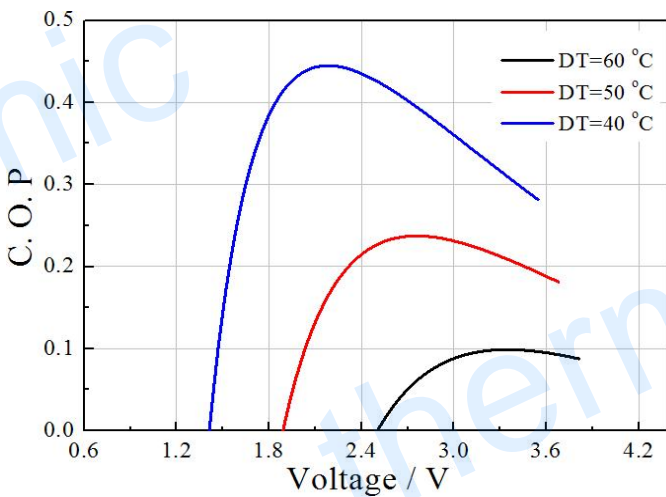
### Performance Curves at $T_h=27\text{ }^\circ\text{C}$



### Performance Curves at $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

**Remark:** The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

### Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC

**Note:** All specifications subject to change without notice.